



Corrigendum to EN 60512-12-3:2006

English version

Foreword

Replace the last paragraph by:

Annex ZA has been added by CENELEC.

Add Annex ZA (see overleaf):

December 2006

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-58	- ¹⁾	Environmental testing Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58 + corr. December	2004 ²⁾ 2004
IEC 60512-1-1	- ¹⁾	Connectors for electronic equipment - Tests and measurements Part 1-1: General examination - Test 1a: Visual examination	EN 60512-1-1	2002 ²⁾
IEC 60512-12-1	- ¹⁾	Connectors for electronic equipment - Tests and measurements Part 12-1: Soldering tests - Test 12a: Solderability, wetting, solder bath method	EN 60512-12-1	2006 ²⁾
IEC 60512-12-2	- ¹⁾	Connectors for electronic equipment - Tests and measurements Part 12-2: Soldering tests - Test 12b: Solderability, wetting, soldering iron method	EN 60512-12-2	2006 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.